



PRODUCT SPECIFICATION SHEET

PRODUCT TYPE : SMD TA TYPE

NOMINAL FREQ. : 32.768KHz

TXC P/N : 9H03200012

REVISION : S1

PE/RD	QA	MFG
王敬和		
20-Jul-09		

NOTE:

- (1)Lead Free Products are "Directive 2002/95/EC of The European Parliament of 27 January 2003 on the restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment" Compliant (Attachment: SGS Test Report).
- (2)Revision "Sx" is for engineering samples only. PE/RD's approval required.
- (3)Revision "Ax" is production ready. PE, QA and MFG's approval required

RoHS Compliant



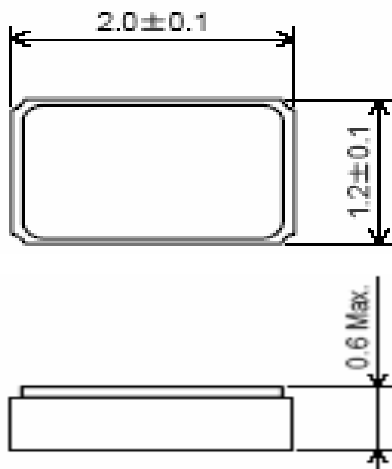
<u>Rev</u>	<u>Revise page</u>	<u>Revise contents</u>	<u>Date</u>	<u>Ref.No.</u>	<u>Reviser</u>
A	NA	Initial release	20-Jul-09	-	Alan Cheng

ELECTRICAL SPECIFICATIONS

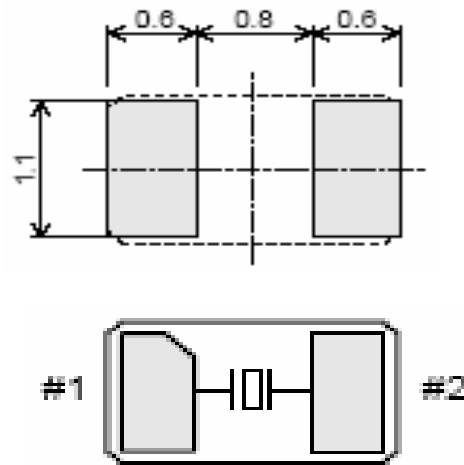
	Parameters	SYM.	Electrical Spec.				Notes
			MIN	TYPE	MAX	UNITS	
1	Nominal Frequency	F0	32.768			KHz	-
2	Frequency Tolerance	-	± 20			ppm	at 25 °C
3	Driver Level	DL	-	0.1	0.5	uW	-
4	Load Capacitance	CL	12.5			pF	-
5	Series Resistance	-	-	-	90	KΩ	-
6	Peak Temperature (Frequency)	-	20	25	30	°C	at 25 °C ±5°C
7	Frequency-Temperature coefficient	-	-	-	-4.0*10 ⁻⁸	°C ²	-
8	Storage Temperature	-	-55	~	125	°C	-
9	Operating Temperature	-	-40	~	85	°C	-
10	Shunt Capacitance	C0	-	1.3	-	pF	-
11	Motional Capacitance	C1	-	6.5	-	fF	-
12	Insulation Resistance	-	500	-	-	MΩ	at DC 100V±15V
13	Aging	-	±3			ppm	1st Year

DIMENSIONS

(UNIT:mm)

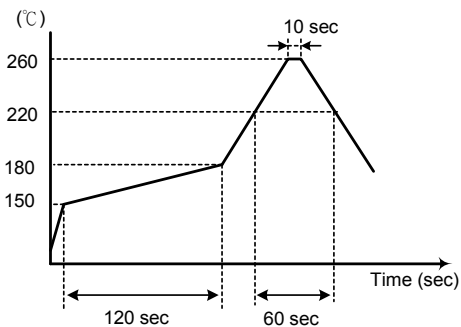
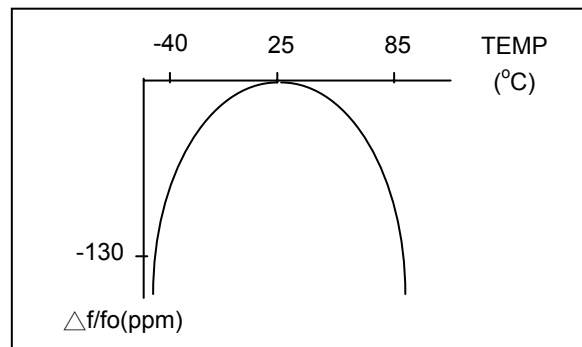

RECOMMENDED SOLDER PAD

(UNIT:mm)

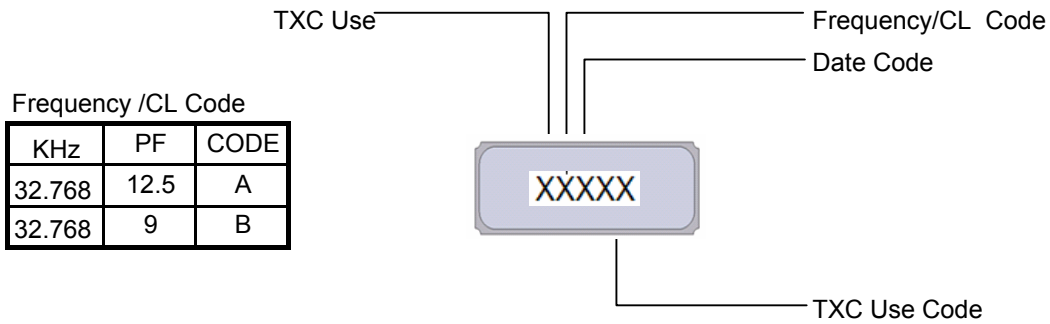

SUGGESTED REFLOW PROFILE

Total time : 200 sec. Max.

Solder melting point :220°C


TEMPERATURE V.S FREQUENCY CURVE


MARKING

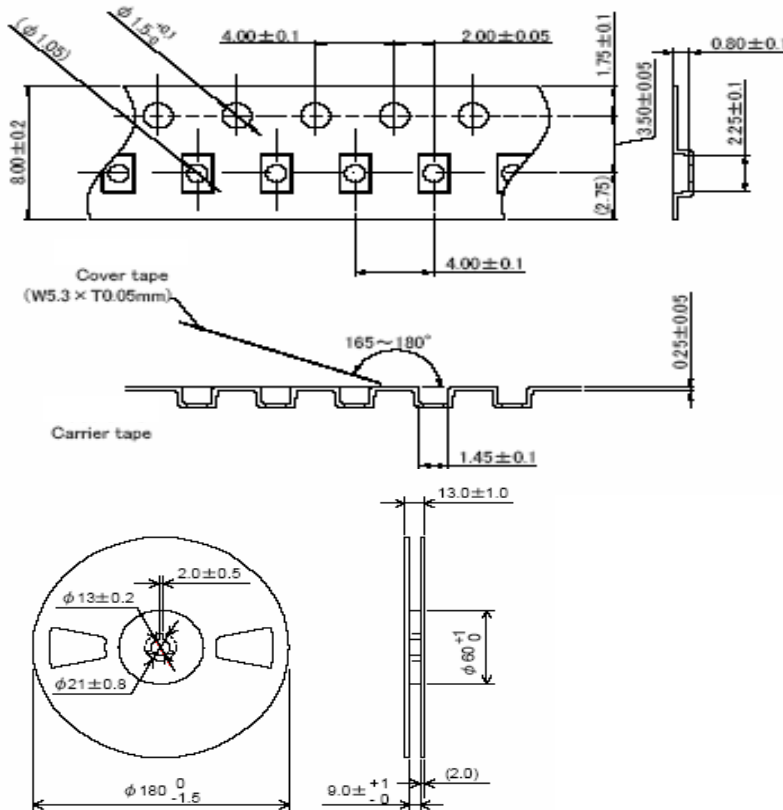


Date Code

YEAR					MONTH											
					JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	OCT	NOV	DEC
2001	2005	2009	2013	2017	A	B	C	D	E	F	G	H	J	K	L	M
2002	2006	2010	2014	2018	N	P	Q	R	S	T	U	V	W	X	Y	Z
2003	2007	2011	2015	2019	a	b	c	d	e	f	g	h	j	k	l	m
2004	2008	2012	2016	2020	n	p	q	r	s	t	u	v	w	x	y	z

This date code will be cycled every four years

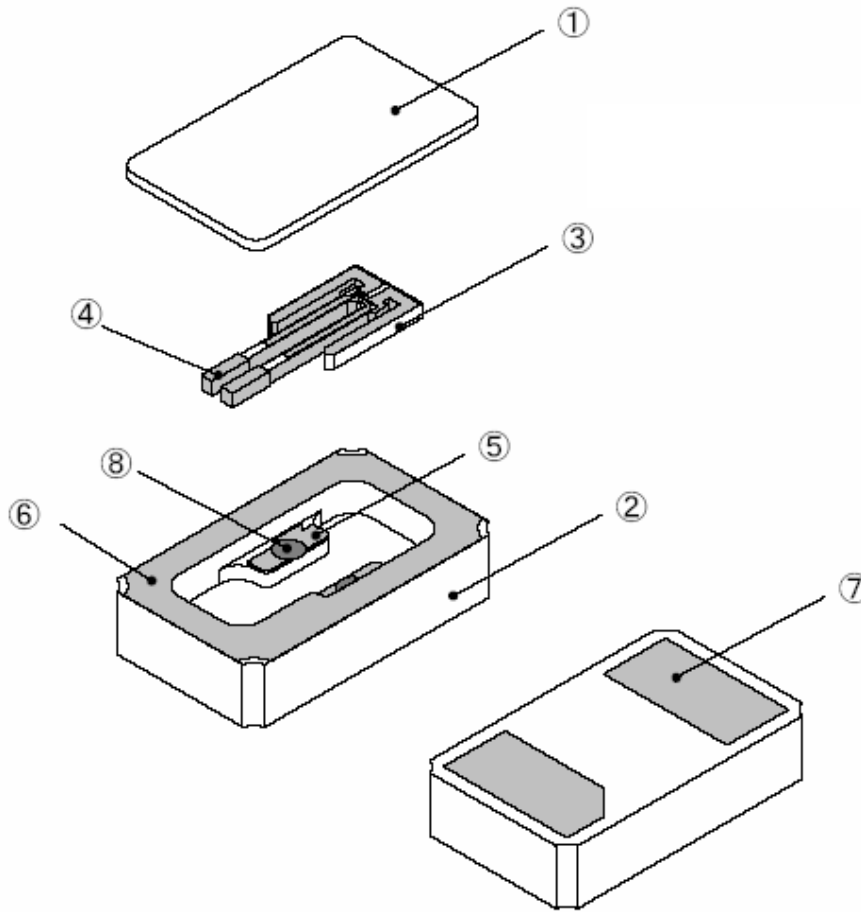
PACKING (UNIT:mm)



Amount	PCS/REEL
	3K

3000 pieces of taped crystal units are put into a packing reels

- REMARK :
- 230 mm (9.05) minimum leader which consist of carrier and/or tape followed by a minimum of 160 mm (6.3) of empty carrier tape sealed with cover tape.
 - 160 mm (6.3) minimum trailer of empty carrier tape sealed with cover tape.

■ STRUCTURE ILLUSTRATION


NO	COMPONENTS	MATERIALS	QTY	FINISH/SPECIFICATIONS
1	Lid	Kovar (Fe/Co/Ni)	1	-
2	Base(Package)	Ceramic(Al_2O_3)	1	Color Black
3	Crystal blank	SiO_2	1	-
4	Electrode	Noble Metal	2	-
5	Internal terminals	Au	2	Tungsten metallize + Ni plating + Au plating
6	Metallize for sealing	Au	1	Tungsten metallize + Ni plating + Au plating
7	PAD	Au	2	Tungsten metallize + Ni plating + Au plating
8	Conductive adhesive	Ag	2	Silicon resin

RELIABILITY SPECIFICATIONS
1. Mechanical Endurance

No.	Test Item	Test Methods	REF. DOC
1.1	Drop Test	150 cm height, fall freely onto concrete floor 3 times.	JIS C6701
1.2	Mechanical Shock	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times. 1m sec. duration time	JIS C60068-2-27
1.3	Vibration	Frequency range 10 ~ 55 Hz Amplitude 1.5 mm,20G Sweep time 1 minute Perpendicular axes each test time 2 hours (Total test time 6 hours)	JIS C60068-2-6
1.4	Solderability	Temperature 255 °C ± 5°C Immersing depth 0.5 mm minimum Immersion time 3.5 ± 0.5 seconds Flux Rosin resin methyl alcohol solvent (1 : 4)	MIL-STD-883E

2. Environmental Endurance

No.	Test Item	Test Methods	REF. DOC
2.1	Resistance To Soldering Heat	Pre-heat temperature 160 °C Pre-heat time 90 ± 10 sec. Test temperature 260 ± 5 °C Test time 5 ± 1 sec.	MIL-STD-202F
2.2	High Temp. Storage	+ 100 °C ± 3 °C for 1000 ± 12 hours	JIS C600682-2
2.3	Low Temp. Storage	- 40 °C ± 3 °C for 1000 ± 12 hours	JIS C600682-1
2.4	Thermal Shock	Total 100 cycles of the following temperature cycle 	JIS C0025
2.5	Pressure Cooker Storage	121 ± 3°C, RH100%, 2 bar, for 240 hours	JIS C6701
2.6	High Temp & Humidity	40°C ± 3°C, RH 90~95% , 1000Hrs	JIS C600682-3